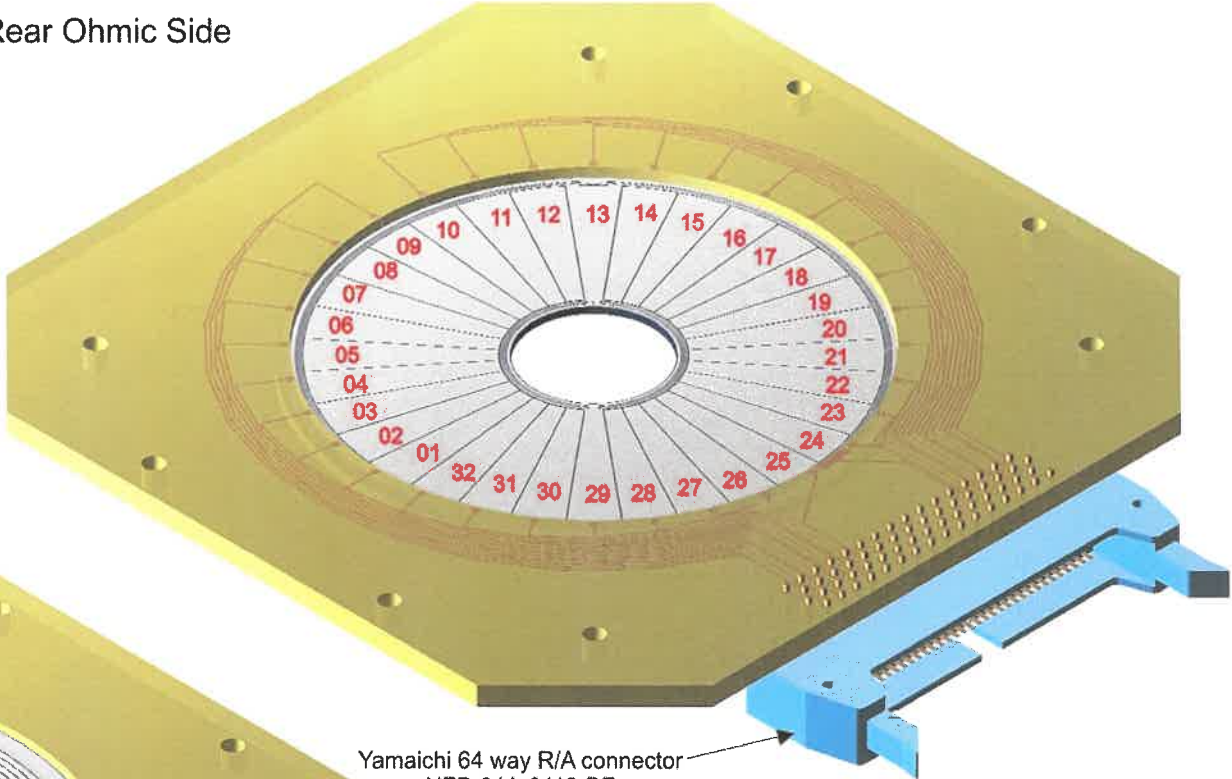
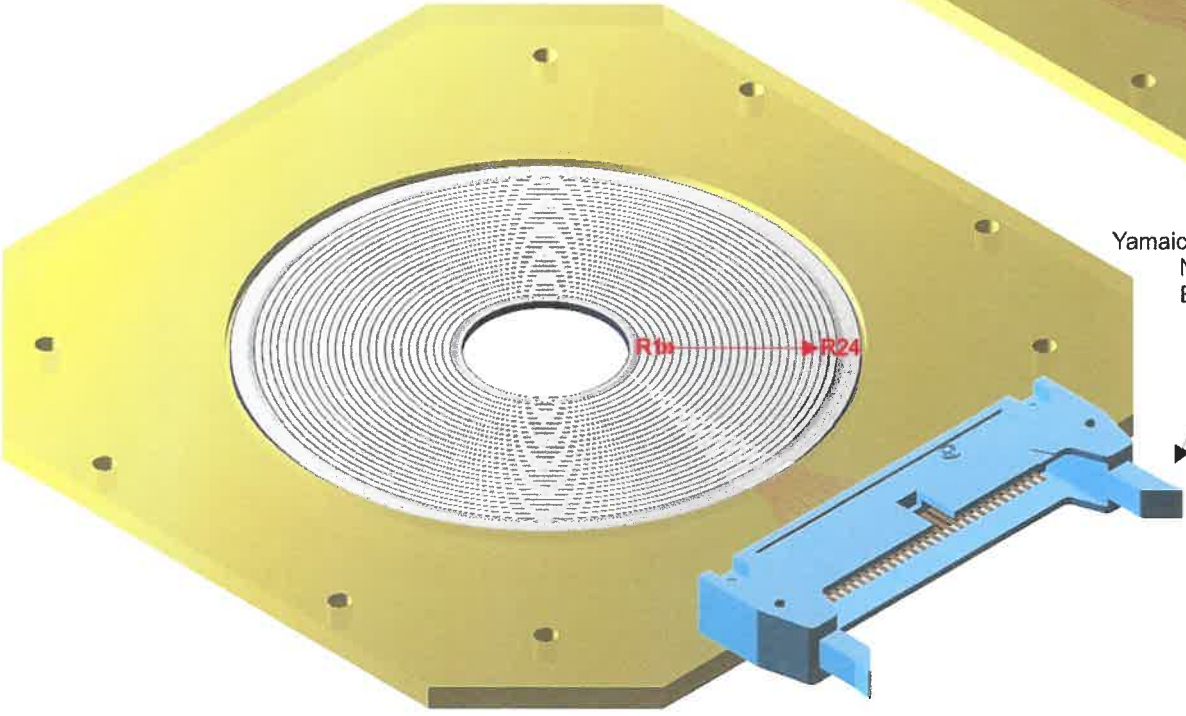


Rear Ohmic Side

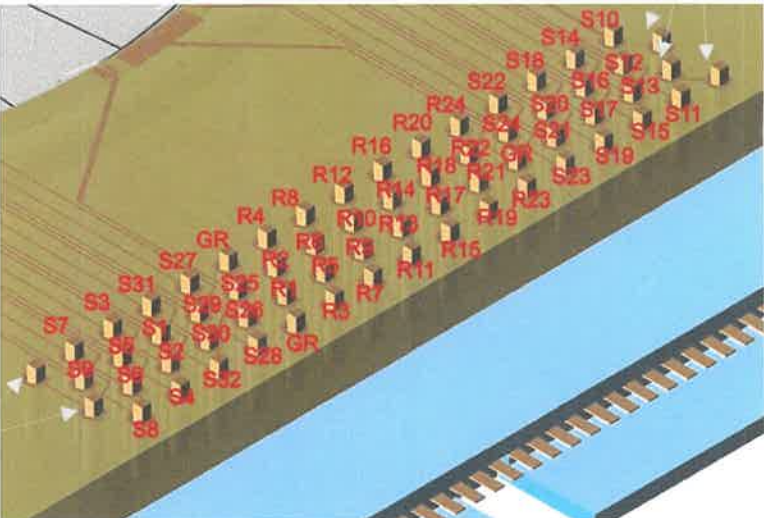


Front Junction Side



Spare 3 Pins Commoned

Yamaichi 64 way R/A connector
NFP-64A-0112-BF
Exiting Front Side.



Spare 2 Pins Commoned

For pin out please refer to A-3300

Drawn N.W	Checked S.W	Date 05/06/2007	Tolerances Unless Stated	Outputs Via: Yamaichi 4 Row Right Angled Connector NFP-64A-0112-BF	Title. S3 3D Assembly. Front and Rear View.
Des. Appd.			Package O/D $\pm 0.1\text{mm}$	Mating connector: Yamaichi NFS-64A Series	
Customer			Package Hole $\pm 0.05\text{mm}$	Potted Wire Bonds: No	
			Package Hole Pos'n $\pm 0.1\text{mm}$	Substrate Number: A-3329	
			Detector O/D $\pm 20.0\mu\text{m}$	Substrate Material: 2.4mm thick FR4 PCB material.	
				Connector Orientation: To exit front junction side.	

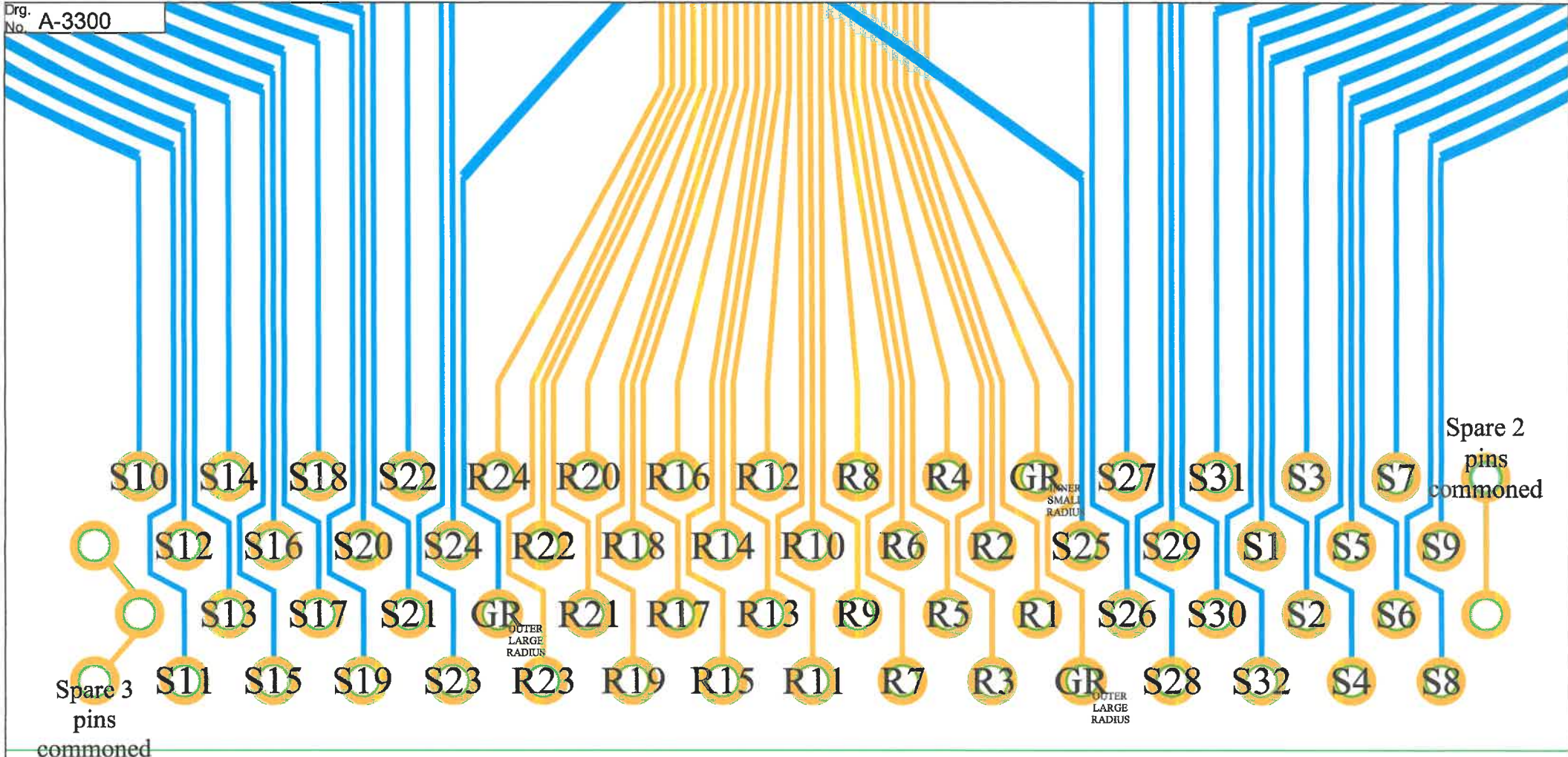


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Scale N/A | Dims In. mm | Drg No A-3330



Drawn. S.W	Checked. A.N	Date 22/05/2007	Tolerances Unless Stated		Material - Black FR4 3.2 mm Total Thickness		Title. S3 PCB Pin-Out.
Design Approved			Package O/D ± 0.1mm	Plating - Soft Au on 1 oz Cu			
			Package Hole Ø ± 0.05mm	Solder Resist Front - N/A	Front Coverlay- N/A		
			Package Hole Pos'n ± 0.1mm	Solder Resist Rear - N/A	Rear Coverlay- N/A		
CUSTOMER			Material Thickness ± 0.1	Ledge - 1.6 mm from Top Surface			

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Scale: 6.5:1 | Dims In. mm | Drg. No. A-3300